



1. Material:

Insert Molding: LCP UL 94V-0 Black
 Contact: Copper alloy, T=0.20mm
 Shell: SPCC, T=0.50mm

2. Electrical

- 1.1. Rated Voltage: 40V AC/DC maximum
- 1.2. Rated Current: 0.3A max.
- 1.3. Dielectric strength: 150V AC/1 minute
- 1.4. Insulation Resistance: 150V DC 10MΩ min.
- 1.5. Contact Resistance: 30mΩ Max.

3. Mechanical

- 2.1. Insertion Force Max: 4.0kgf max.
- 2.2. Removal Force Min: 1.0kgf min. , 4.0kgf max.
- 2.3. Durability: 10000 cycles at 100±50 cycles per hour

4. Plating

- 4.1. Terminal: Contact area: 1u" gold plate over 50u" NI min.
Solder area: 100u" pure TIN plate over 50u" NI min.
- 4.2. Shell: Ni: 100u" min.

5. Ambient Temperature: -55°C To +85°C

RECOMMEND PCB LAYOUT (T=1.00)
PCB TOLERANCE: ±0.05

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| CMTDDZ 东莞市田都科技有限公司 Dongguan TianDu Technology Co. Ltd. | | | |
| X. ± 0.30 | APPD: | TITLE: | |
| .X ± 0.25 | | HDMI A 19P SMT | |
| .XX ± 0.20 | CHKD: | 不带凸包 | |
| .XXX ± | | PART NO: | |
| X' ± 1" | DR: ERIC | DWG NO: T15-19F02-A 镀金 | |
| .X' ± 0.5" | | SCALE: 1:1 | SHEET: 10F1 |
| UNITS: mm | | REV: A | |

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| C | 取消侧面凸点, 外壳增加凸包, 修改下料片 | 2018/07/21 |
| B | 取消外壳上中点, 增加侧面凸点, 修改料片宽度 | 2017/08/29 |
| A | 初版发行 | 2017/07/07 |
| REV | DESCRIPTION | DATE |